ON Semiconductor

UPDATE CHANGE NOTIFICATION # 16658

Generic Copy

Issue Date: 29-Nov-2011

TITLE: Added Wafer Capacity at United Microelectronics Corporation

PROPOSED FIRST SHIP DATE: 15-Mar-2012

AFFECTED CHANGE CATEGORY(S): Wafer Fab

ADDITIONAL RELIABILITY DATA: PowerFET Business Unit

SAMPLES: Contact your local ON Semiconductor Sales Office or Brian Goodburn <brian.goodburn@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or or Jason Jeong <Jason.Jeong@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:
ON Semiconductor is adding Trench (T1) MOSFET wafer fabrication capacity at the United Microelectronics Corporation wafer facility.

This is an updated notification to FPCN #16658 announcing to Customers that ON Semi is revising their change over date for Die sourcing from the UMC Wafer Fab facility. Products will now have a Date Code of the Work Week 12, 2012 or newer.

List of affected General Parts:

NTGS4111PT1G	NTJS4151PT1G	NTR4171PT1G
NTHD4102PT1G	NTK3139PT1G	NTS2101PT1G
NTHD4102PT1H	NTK3139PT1H	NTS2101PT1H
NTHS4101PT1G	NTK3139PT5G	NTS4101PT1G
NTJD1155LT1G	NTK3139PT5H	NTS4173PT1G
NTJD4105CT1G	NTR2101PT1G	NTZD3152PT1G
NTJD4105CT1H	NTR2101PT1H	NTZD3152PT1H
NTJD4105CT2G	NTR4101PT1G	NTZS3151PT1G
NTJS3151PT1G	NTR4101PT1H	NTZS3151PT1H